Materials Declaration

Package	SOIC
Body Size	150 mils
LeadCount	14
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	1.04 E-02	66024
SiO2 Filler	85	8.88 E-02	561201
Phenol Resin	3	3.13 E-03	19807
Antimony_Sb2O3	1.5	1.57 E-03	9904
Brominated Resin	0.5	5.22 E-04	3301

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.88 E-02	308274
Fe	2.35	1.18 E-03	7430
P	0.03	1.50 E-05	95
Zn	0.12	6.00 E-05	379

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	4.45 E-04	2813

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.51 E-03	9.55 E+03

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.09 E-04	1952

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.30 E-03	8198

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.22 E-05	267
Ag Filler	75	1.27 E-04	801

Package Totals

Weight (g)	PPM
1.58 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	SOIC
Body Size	150 mils
LeadCount	14
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	1.04 E-02	66024
SiO2 Filler	85	8.88 E-02	561201
Phenol Resin	3	3.13 E-03	19807
Antimony_Sb2O3	1.5	1.57 E-03	9904
Brominated Resin	0.5	5.22 E-04	3301

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.88 E-02	308274
Fe	2.35	1.18 E-03	7430
P	0.03	1.50 E-05	95
Zn	0.12	6.00 E-05	379

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	4.45 E-04	2813

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.28 E-03	8.12 E+03
Pb	15	2.27 E-04	1.43 E+03

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.09 E-04	1952

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.30 E-03	8198

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.22 E-05	267
Ag Filler	75	1.27 E-04	801

Package Totals

Weight (g)	PPM
1.58 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010E
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010E

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Note: The information provided in this declaration are true to the best of ADI's knowledge
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